

FORM PTO-1449 (MODIFIED)

ATTORNEY DOCKET NO.
SP01-302

SERIAL NO.

LIST OF PATENTS AND
PUBLICATIONS
FOR APPLICANTS INFORMATION
DISCLOSURE STATEMENT

10/035659

APPLICANT Karl Heinz Buchanan, et al.

FILING DATE
October 26, 2001

GROUP: 1731

REFERENCE DESIGNATION

U.S. PATENT DOCUMENTS

| Examiner Initial | | Document Number | Date | Name | Class | Sub- Class | Filing Date if Approp. |
|---------------------|----|-----------------|------|------|-------|---------------|---------------------------|
| | AA | | | | | | |
| | AB | | | | | | |
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| | AI | | | | | | |
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| | AK | | | | | | |

FOREIGN PATENT DOCUMENTS

| | | Document Number | Date | Country | Class | Sub- Class | Translation Yes No |
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| | AL | | | | | | |
| | AM | | | | | | |
| | AN | | | | | | |
| | AO | | | | | | |
| | AP | | | | | | |
| | AQ | | | | | | |

OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)

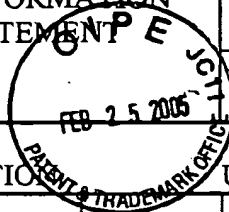
| | |
|----|--|
| AR | W.P. Maszara, "Silicon-On-Insulator by Wafer Bonding: A Review" J. Electrochemical Society, Inc., Vol. 138, No.1, January 1991 |
|----|--|

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DATE CONSIDERED:

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 809: draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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| FORM PTO-1449 (MODIFIED) | ATTORNEY DOCKET NO. | SERIAL NO. |
| LIST OF PATENTS AND PUBLICATIONS FOR APPLICANTS INFORMATION DISCLOSURE STATEMENT | SP01-302 | 10/035659 |
| APPLICANT: COOK, et al. | | |
| FILING DATE 10/26/2001 | | GROUP: 1731 |



| REFERENCE DESIGNATION | | | | U.S. PATENT DOCUMENTS | | | |
|-----------------------|----|-----------------|----------|-----------------------|-------|-----------|------------------------|
| Examiner Initial | | Document Number | Date | Name | Class | Sub-Class | Filing Date if Approp. |
| | AA | 4,186,999 | 2/5/80 | Harwood et al | 350 | 96.21 | |
| | AB | 4,530,452 | 7/23/85 | Balyasny et al | 225 | 96 | |
| | AC | 4,626,068 | 12/2/86 | Caldwell | 350 | 96.34 | |
| | AD | 5,183,710 | 2/2/93 | Gerbino | 428 | 405 | |
| | AE | 5,346,583 | 9/13/94 | Basavanhally | 156 | 629 | |
| | AF | 5,451,547 | 9/19/95 | Himi et al | 437 | 225 | |
| | AG | 5,452,122 | 9/19/95 | Tsuneda et al | 359 | 281 | |
| | AH | 5,579,421 | 11/26/96 | Duvall et al | 385 | 14 | |
| | AI | 5,631,986 | 5/20/97 | Frey et al | 385 | 78 | |
| | AJ | 5,846,638 | 12/8/98 | Meissner | 428 | 220 | |
| | AK | 5,852,622 | 12/22/98 | Meissner et al | 372 | 39 | |
| | AL | 5,989,372 | 11/23/99 | Momoda et al | 156 | 89.11 | |
| | AM | 6,030,883 | 2/29/00 | Nishimoto et al | 438 | 455 | |
| | AN | 6,048,103 | 4/11/00 | Furukata et al | 385 | 73 | |
| | AO | 6,249,619 | 6/19/01 | Bergmann et al | 385 | 11 | |
| | AP | 6,275,336 | 8/14/01 | Yoshikawa et al | 359 | 484 | |
| | AQ | 6,359,733 | 3/19/02 | Iwatsuka et al | 359 | 500 | |
| | AR | 6,583,029 | 6/24/03 | Abe et al | 438 | 455 | |
| | AS | 2002/0108556 | 8/15/02 | Ebbers | 117 | 2 | |
| | AT | 2003/0079503 | 5/1/03 | Cook et al | 65 | 407 | |
| | AU | 2003/0079823 | 5/1/03 | Sabia | 156 | 99 | |
| | AV | 2003/0081906 | 5/1/03 | Filhaber et al | 385 | 60 | |
| | AW | 2003/0206345 | 11/6/03 | Sabia et al | 359 | 484 | |
| | AX | 2003/0206347 | 11/6/03 | Sabia et al | 359 | 484 | |
| | AY | 2003/0081930 | 5/1/03 | Filhaber et al | 385 | 147 | |
| | AZ | 4,960,331 | 10/2/90 | Goldman et al | 356 | 350 | |
| | BA | 5,319,483 | 6/7/94 | Krasinski et al | 359 | 113 | |
| | BB | 5,441,803 | 8/15/95 | Meissner | 428 | 220 | |
| | BC | 5,689,519 | 11/18/97 | Fermann et al | 372 | 18 | |
| | BD | 6,120,917 | 9/19/00 | Eda | 428 | 692 | |
| | BE | 6,548,176 | 4/15/03 | Gwo | 428 | 420 | |
| | BF | 6,621,630 | 9/16/03 | Iwatsuka | 359 | 484 | |
| | BG | 5,915,193 | 6/22/99 | Tong et al. | 438 | 455 | |
| | BH | 5,785,874 | 7/28/98 | Eda | 216 | 24 | |
| | BI | 5,932,048 | 8/3/99 | Furukawa et al. | 156 | 153 | |
| | BJ | 6,129,854 | 10/10/00 | Ramsey et al. | 216 | 18 | |
| | BK | 6,153,495 | 11/28/00 | Kub et al. | 438 | 459 | |
| | BL | 6,178,779 | 1/30/01 | Drouart et al. | 65 | 391 | |

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|----|-----------|---------|------------------|----|------|--|
| BM | 6,098,429 | 8/8/01 | Mazabraud et al. | 65 | 392 | |
| BA | 4,407,667 | 10/4/83 | LeNoane et al. | 65 | 3.11 | |

FOREIGN PATENT DOCUMENTS

| | Document Number | Date | Country | Class | Sub-Class | Translation | |
|----|-----------------|----------|----------------------------|-------|-----------|-------------|----|
| | | | | | | Yes | No |
| BO | WO01/98225 | 12/27/01 | PCT | C03C | 27/06 | | |
| BP | WO00/17698 | 3/30/00 | PCT | G02F | 1/09 | | |
| BQ | DE19731075 | 1/21/99 | Germany (English Abstract) | C03C | 29/00 | | |
| BR | DE2130905 | 1/11/73 | Germany (English Abstract) | H01J | 19/56 | | |
| BS | 08-146351 | 6/7/96 | Japan (English Abstract) | G02B | 27/28 | | |
| BT | 2002321947 | 4/25/01 | Japan (English Abstract) | C03C | 27/00 | | |
| BU | 03-115178 | 5/16/91 | Japan (English Abstract) | C04B | 37/00 | | |
| BV | 52-78450 | 7/1/77 | Japan (English Abstract) | C03B | 37/00 | | |
| BW | 1 057 793A1 | 12/6/00 | EPO | C03B | 37/027 | X | |

OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)

| | |
|----|--|
| BX | ONISHI et al., "A novel temperature compensation method for SAW devices using direct bonding Techniques," <i>Ultrasonics Symp</i> , 1997, IEEE Proceedings, 5-8 Oct, 1997 Pages 227-230. |
| BY | Arthur Landrock; "Surface Preparation of Adherends"; Adhesives Technology Handbook; 1985; page 117-118 |
| BZ | A. Sayah, D. Solignac, T. Cueni, M.A.M. Gijis, "Development of novel low temperature bonding technologies for microchip chemical analysis applications," <i>Sensors and Actuators</i> , 84 August (2000) pp. 103-108. |
| CA | P. Rangsten, O. Vallin, K. Hermansson, Y. Backlund, "Quartz-to-Quartz Direct Bonding," <i>Journal of the Electrochemical Society</i> , V. 146, N. 3, pp. 1104-1105, (1999). |
| CB | H. Nakanishi, T. Nishimoto, M. Kanai, T. Saitoh, R. Nakamura, T. Yoshida, S. Shoji, "Condition optimization, reliability evaluation of SiO ₂ -SiO ₂ HF bonding and its application for UV detection micro flow cell," <i>Sensors and Actuators</i> , V. 83, pp. 136-141, May 2000. |
| CC | A. Yamada, T. Kawasaki, M. Kawashima, "Bonding Silicon wafer to Silicon Nitride With Spin-on Glass as Adhesive," <i>Electronics Letters</i> , March 26, 1987, Vol. 23, No. 7 Pages 314-315. |
| CD | D.J. Harrison, Karl Fluri, Kurt Seiler, Zhonghui Fan, Carlo S. Effenhauser, Andreas Manz, "Micromachining a Miniaturized Capillary Electrophoresis-Based Chemical Analysis System on a Chip," <i>Science</i> , V. 261, August 13 (1993) 895-897. |
| CE | Dong-Woon Shin, Doo-Jin Choi, Geung-Ho Kim, "The Stacking Faults and Their Strain Effect at the Si/SiO ₂ Interfaces of a Directly Bonded SOI (silicon on insulator)," <i>Thin Solid Films</i> , V. 346, pp. 169-173, 1999. |
| CF | Q-Y. Tong, T-H Lee, and U. Gosele, "The Role of Surface Chemistry in Bonding of Standard Silicon Wafers," <i>J. Electrochemical Society</i> V. 144, N. 1, pp. 384-389, January 1997 |
| CG | |

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DATE CONSIDERED:

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609: draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.